

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	778	mosfet and (chip die ic) same wire and (lead loc) and (encapsulant mold\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/30 12:07
L3	1362	(chip die ic) same wire and (loc lead adj2 over adj2 chip) and (encapsulant mold\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/30 12:23
L4	1181	"257"/\$.ccls. and (chip die ic) same wire and (loc lead adj2 over adj2 chip) and (encapsulant mold\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/30 12:08
L5	811	"257"/\$.ccls. and (chip die ic) same wire same (loc lead adj2 over adj2 chip) and (encapsulant mold\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/30 12:09
L6	712	(chip die ic) same wire and (loc lead adj2 over adj2 chip) and (encapsulant mold\$4) and ((die chip die) adj pad stage)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/30 12:24
L7	5	("5394008" "5498901" "5821605" "5917235" "6066887").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/30 13:41